



# STPS30L60CW/CT/CG/CR

## POWER SCHOTTKY RECTIFIER

### MAIN PRODUCT CHARACTERISTICS

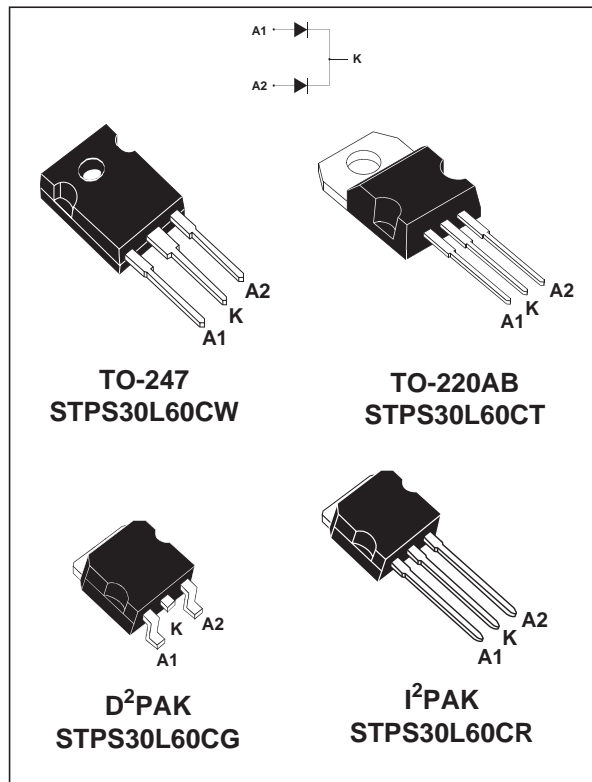
$I_{F(AV)}$	2 x 15 A
$V_{RRM}$	60 V
$T_j(max)$	150°C
$V_F(max)$	0.56 V

### FEATURES AND BENEFITS

- NEGLIGIBLE SWITCHING LOSSES
- LOW FORWARD VOLTAGE DROP
- LOW THERMAL RESISTANCE

### DESCRIPTION

Dual center tap Schottky rectifiers suited for Switched Mode Power Supplies and high frequency DC to DC converters. Packaged in TO-220, D<sup>2</sup>PAK, I<sup>2</sup>PAK and TO-247 this device is intended for use in high frequency inverters.



### ABSOLUTE RATINGS (limiting values, per diode)

Symbol	Parameter		Value	Unit
$V_{RRM}$	Repetitive peak reverse voltage		60	V
$I_{F(RMS)}$	RMS forward current		30	A
$I_{F(AV)}$	Average forward current	$T_c = 130^\circ\text{C}$ $\delta = 0.5$	Per diode 30 Per device	A
$I_{FSM}$	Surge non repetitive forward current	$t_p = 10\text{ ms}$ Sinusoidal	230	A
$I_{RRM}$	Repetitive peak reverse current	$t_p = 2\ \mu\text{s}$ square F=1kHz	2	A
$T_{stg}$	Storage temperature range		- 65 to + 175	°C
$T_j$	Maximum operating junction temperature *		150	°C
dV/dt	Critical rate of rise of reverse voltage		10000	V/ $\mu\text{s}$

\* :  $\frac{dP_{tot}}{dT_j} < \frac{1}{R_{th}(j-a)}$  thermal runaway condition for a diode on its own heatsink

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### THERMAL RESISTANCES

Symbol	Parameter		Value	Unit
$R_{th(j-c)}$	Junction to case	Per diode	1.5	$^{\circ}\text{C}/\text{W}$
		Total	0.8	
$R_{th(c)}$		Coupling	0.1	$^{\circ}\text{C}/\text{W}$

When the diodes 1 and 2 are used simultaneously :  
 $\Delta T_{j(\text{diode } 1)} = P(\text{diode } 1) \times R_{th(j-c)}(\text{Per diode}) + P(\text{diode } 2) \times R_{th(c)}$

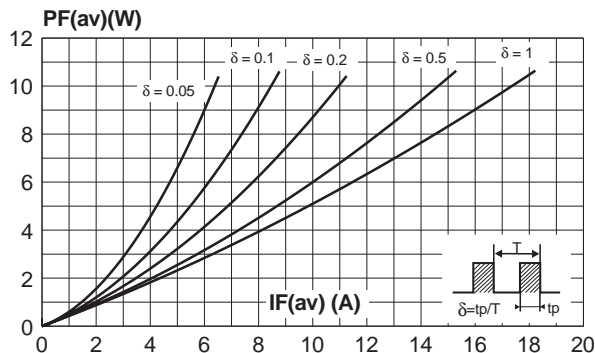
### STATIC ELECTRICAL CHARACTERISTICS (per diode)

Symbol	Parameter	Tests Conditions		Min.	Typ.	Max.	Unit
$I_R^*$	Reverse leakage current	$T_j = 25^{\circ}\text{C}$	$V_R = V_{RRM}$			480	$\mu\text{A}$
		$T_j = 125^{\circ}\text{C}$			77	130	mA
$V_F^*$	Forward voltage drop	$T_j = 25^{\circ}\text{C}$	$I_F = 15\text{ A}$			0.6	V
		$T_j = 125^{\circ}\text{C}$	$I_F = 15\text{ A}$		0.5	0.56	
		$T_j = 25^{\circ}\text{C}$	$I_F = 30\text{ A}$			0.75	
		$T_j = 125^{\circ}\text{C}$	$I_F = 30\text{ A}$		0.65	0.7	

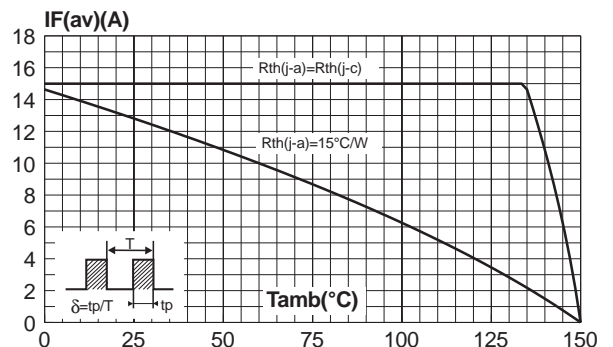
Pulse test : \*  $t_p = 380\ \mu\text{s}$ ,  $\delta < 2\%$

To evaluate the maximum conduction losses use the following equation :  
 $P = 0.42 \times I_{F(AV)} + 0.009 I_{F(RMS)}^2$

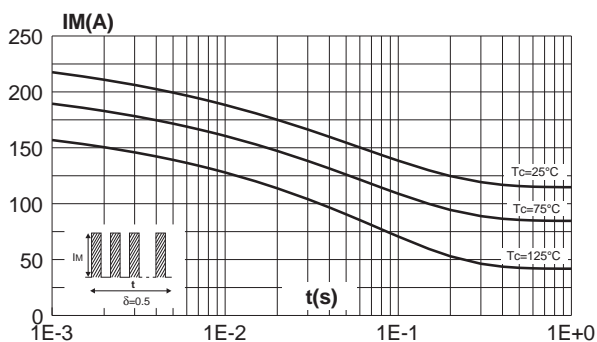
**Fig. 1:** Average forward power dissipation versus average forward current (per diode).



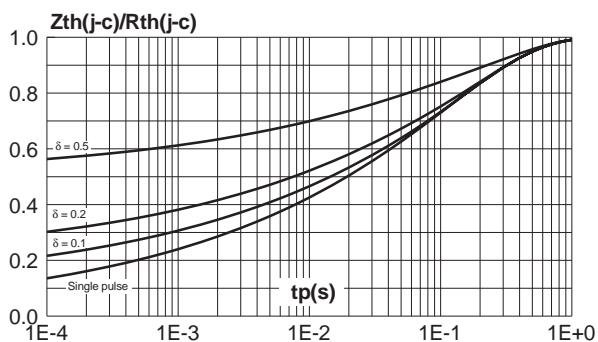
**Fig. 2:** Average forward current versus ambient temperature ( $\delta = 0.5$ , per diode).



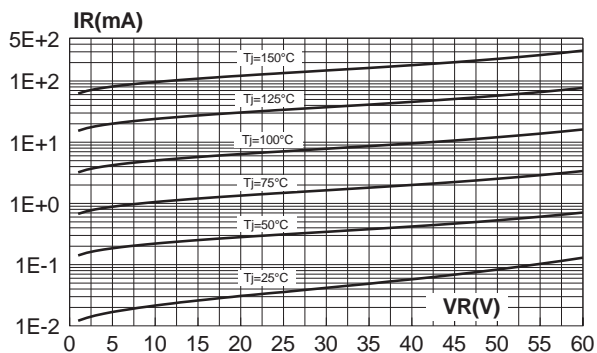
**Fig. 3:** Non repetitive surge peak forward current versus overload duration (maximum values, per diode).



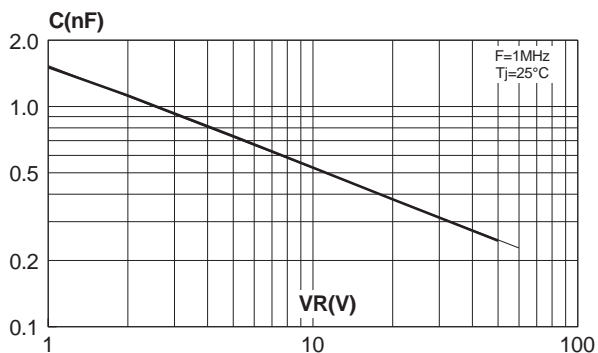
**Fig. 4:** Relative variation of thermal impedance junction to case versus pulse duration.



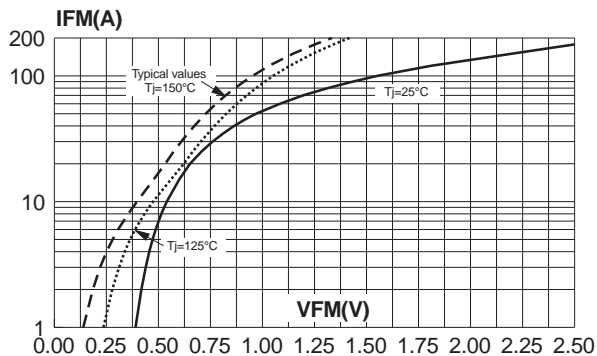
**Fig. 5:** Reverse leakage current versus reverse voltage applied (typical values, per diode).



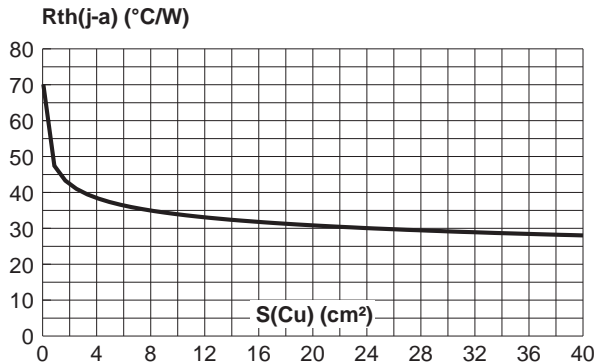
**Fig. 6:** Junction capacitance versus reverse voltage applied (typical values, per diode).



**Fig. 7:** Forward voltage drop versus forward current (maximum values, per diode).



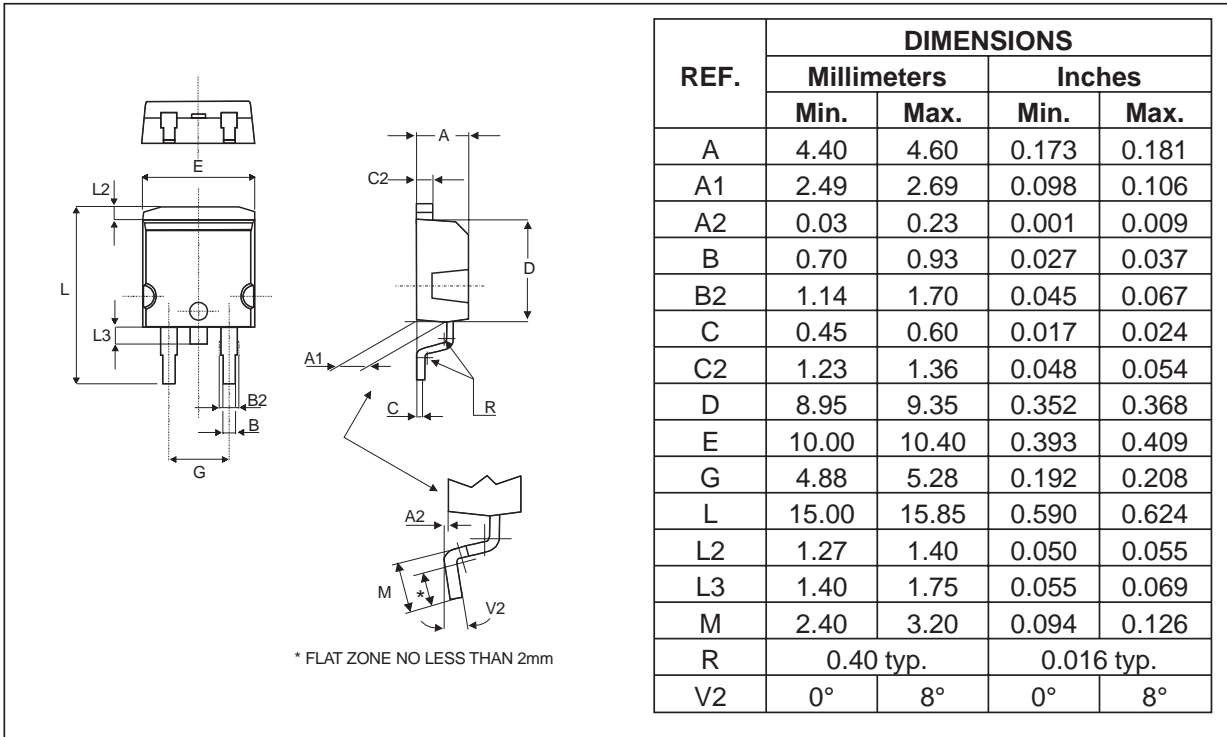
**Fig. 8:** Thermal resistance junction to ambient versus copper surface under tab for D<sup>2</sup>PAK (Epoxy printed circuit board FR4, copper thickness: 35µm)



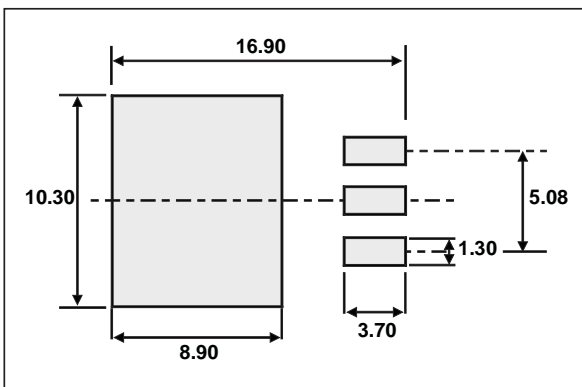
**STPS30L60CW/CT/CG/CR**

**PACKAGE MECHANICAL DATA**

D<sup>2</sup>PAK

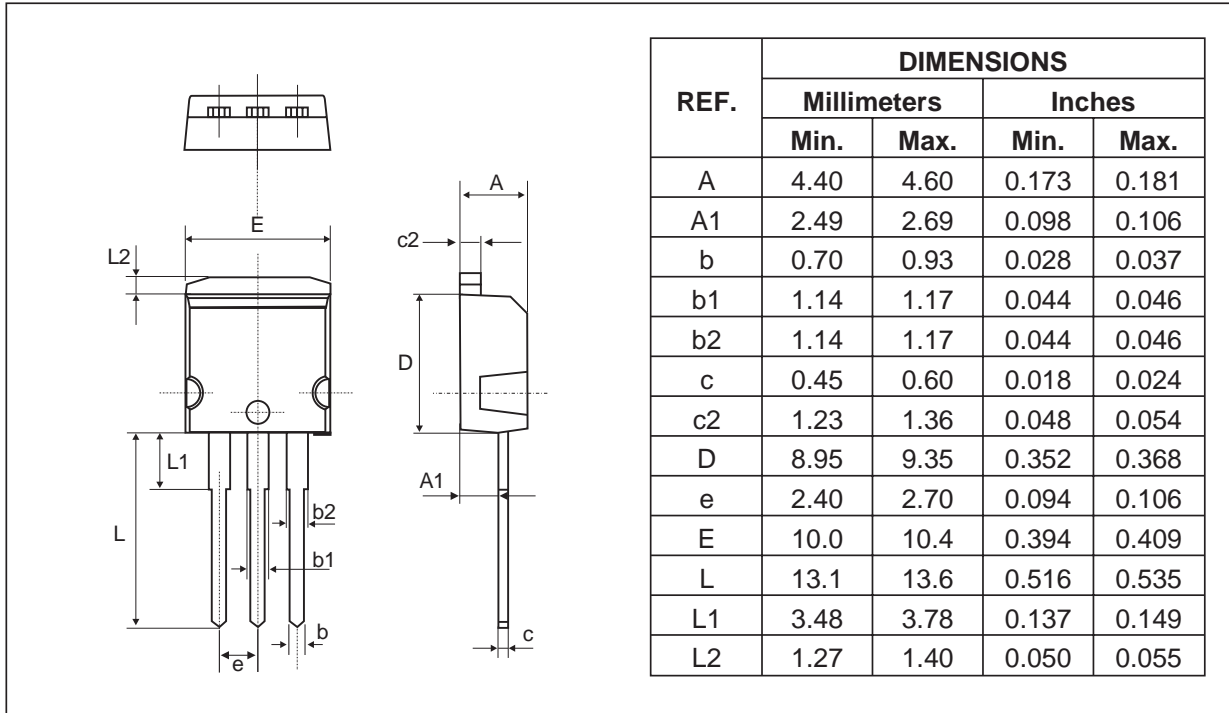


**FOOTPRINT**



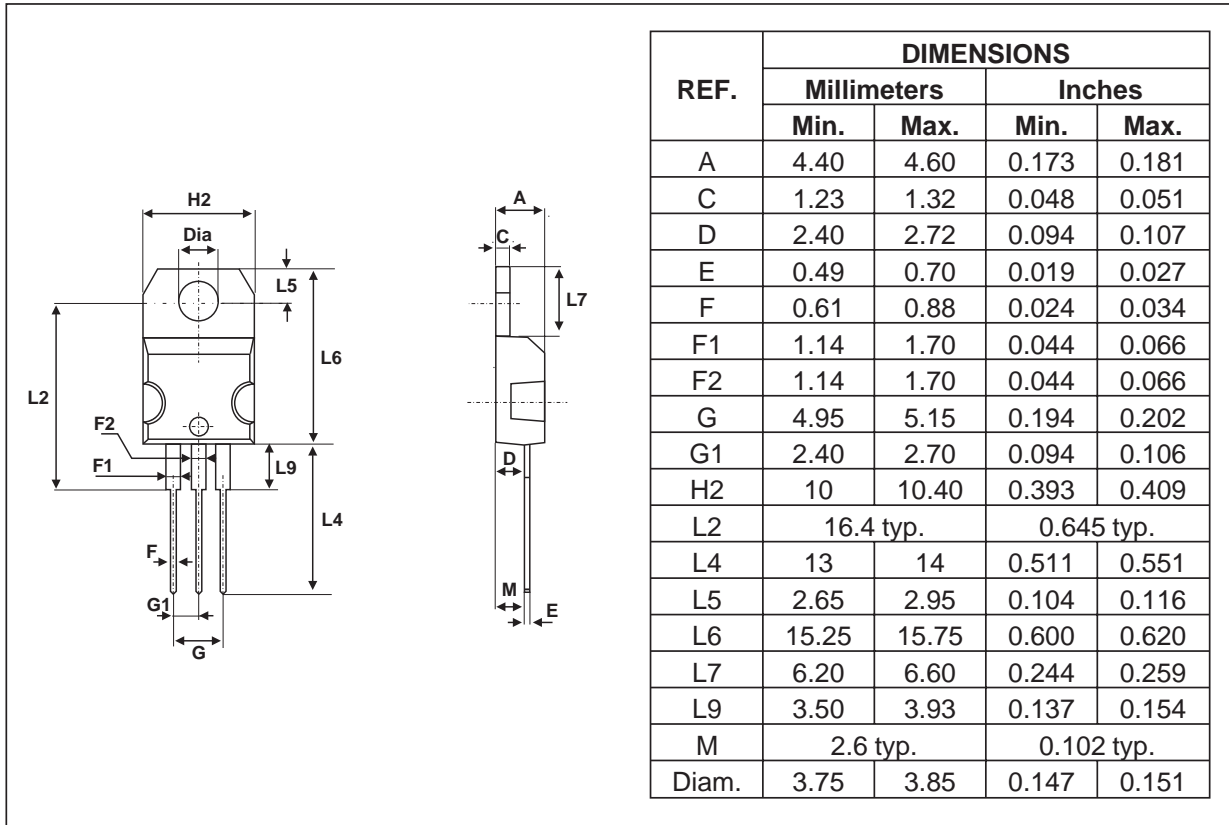
PACKAGE MECHANICAL DATA

I<sup>2</sup>PAK



PACKAGE MECHANICAL DATA

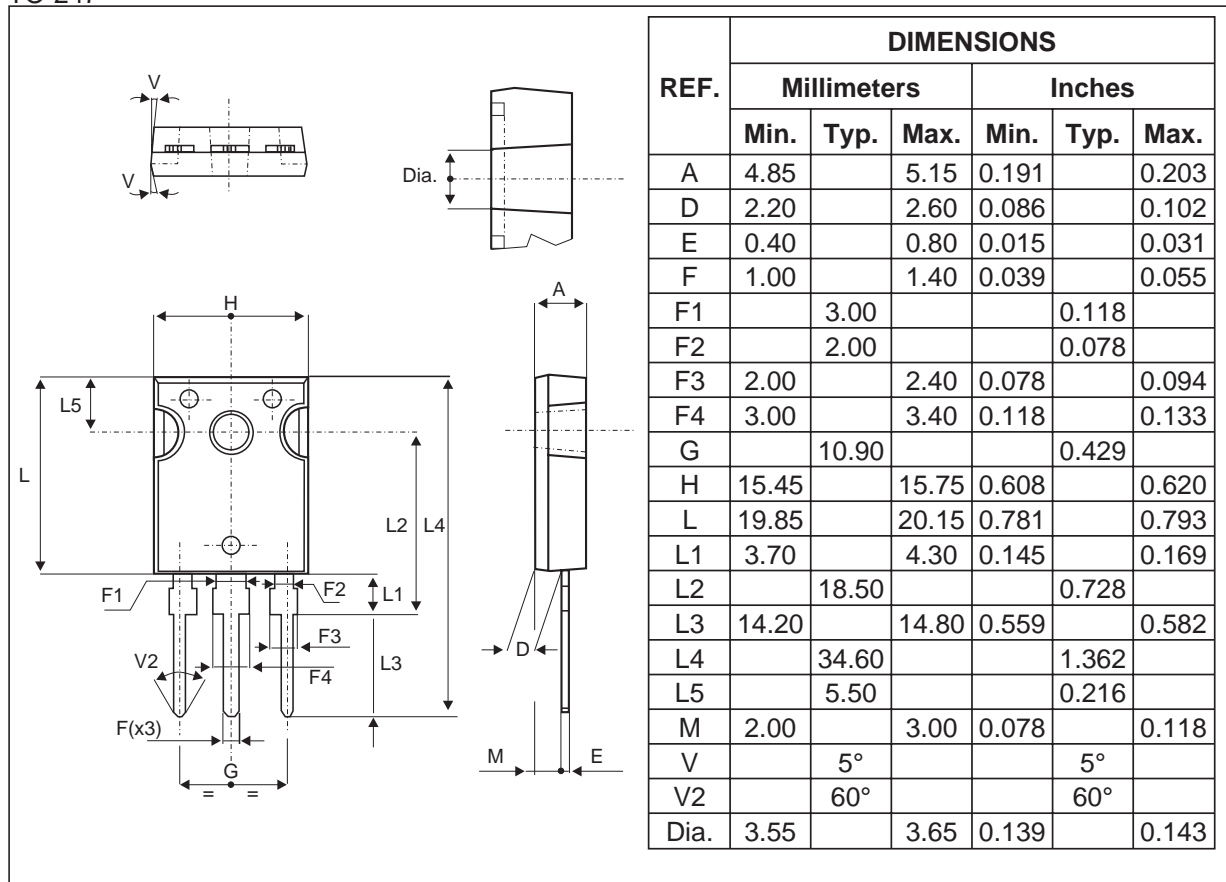
TO-220AB



**STPS30L60CW/CT/CG/CR**

**PACKAGE MECHANICAL DATA**

TO-247



- Cooling method : C
- Recommended torque value : 0.8m.N
- Maximum torque value : 1.0m.N

Ordering type	Marking	Package	Weight	Base qty	Delivery mode
STPS30L60CW	STPS30L60CW	TO-247	4.4g	50	Tube
STPS30L60CT	STPS30L60CT	TO-220AB	2.3g	50	Tube
STPS30L60CG	STPS30L60CG	D <sup>2</sup> PAK	1.5g	50	Tube
STPS30L60CR	STPS30L60CR	I <sup>2</sup> PAK	1.49 g	50	Tube

- Epoxy meets UL94,V0

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